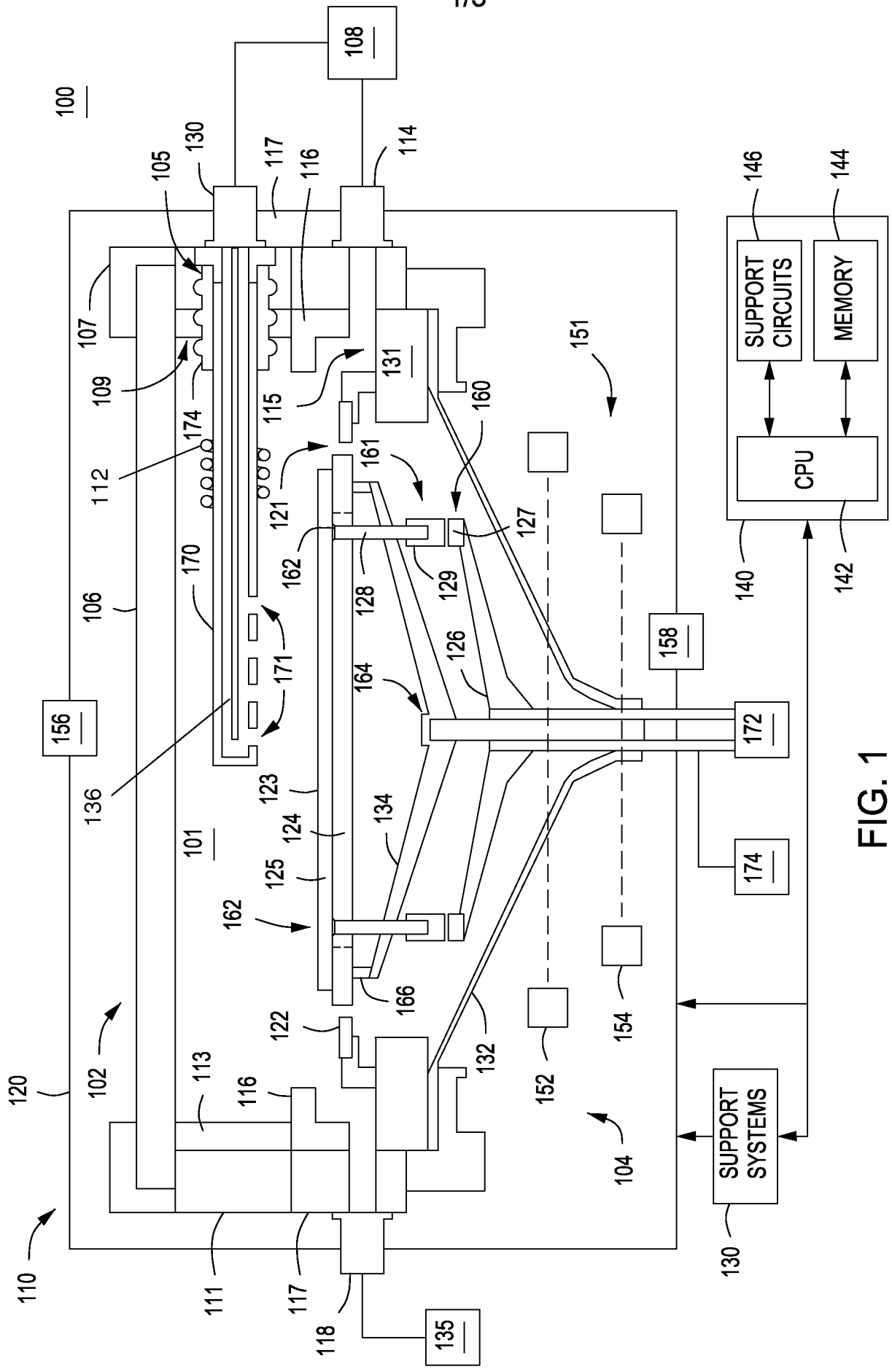

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SUPPORT SYSTEMS
146
144
SUPPORT CIRCUITS
MEMORY
CPU
140
142
151
172
174

FIG. 1

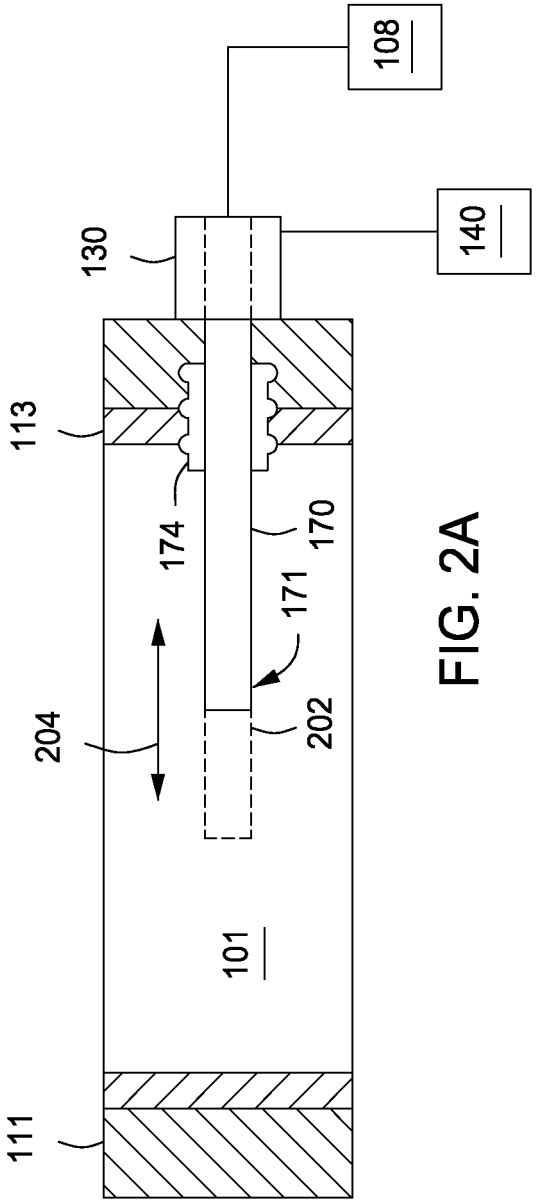

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FIG. 2A

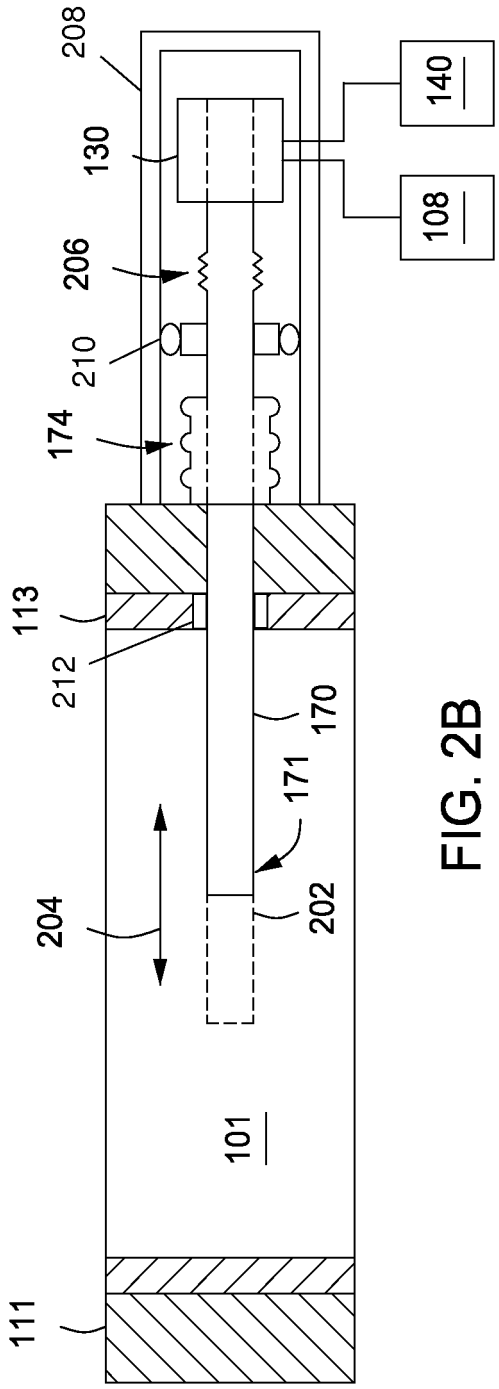

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212
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111

FIG. 2B

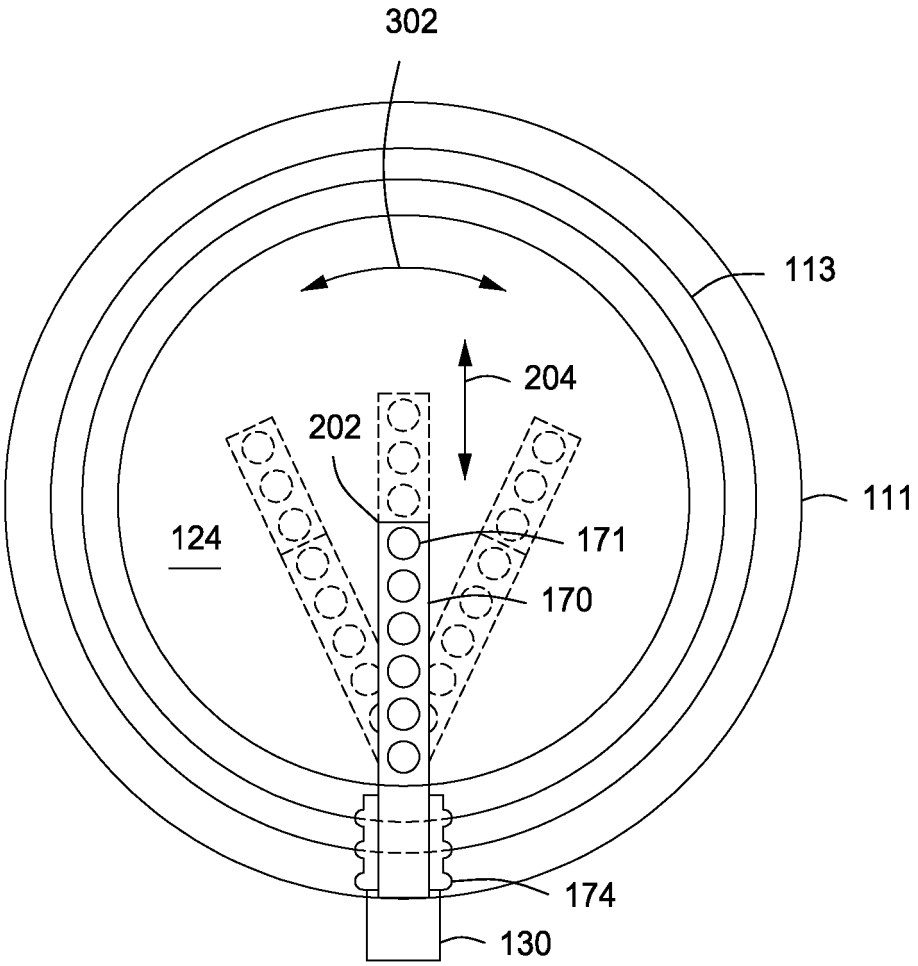

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FIG. 3

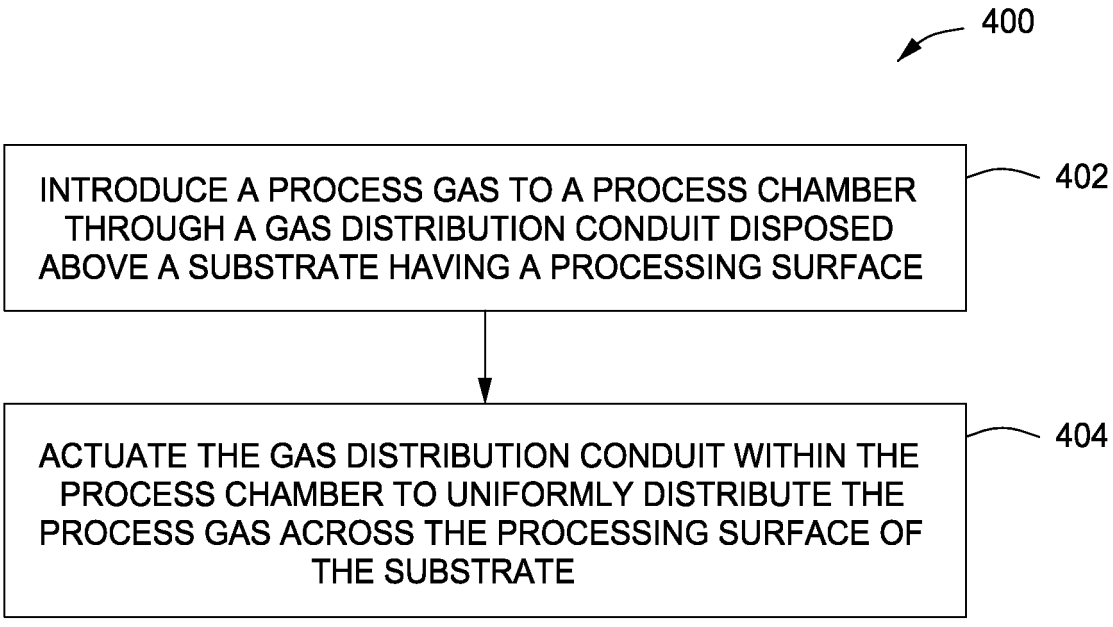

400
INTRODUCE A PROCESS GAS TO A PROCESS CHAMBER THROUGH A GAS DISTRIBUTION CONDUIT DISPOSED ABOVE A SUBSTRATE HAVING A PROCESSING SURFACE
402
ACTUATE THE GAS DISTRIBUTION CONDUIT WITHIN THE PROCESS CHAMBER TO UNIFORMLY DISTRIBUTE THE PROCESS GAS ACROSS THE PROCESSING SURFACE OF THE SUBSTRATE
404

FIG. 4